







Service d'Electronique, Détecteurs, et Informatique (Irfu/SEDI) Laboratoire Léon Brillouin (Iramis/LLB)

Neutron detectors based on the MICRO-Mesh Gaseous Structure (MICROMEGAS)

A.Menelle (CEA/LLB), G.Tsiledakis, A.Delbart , D.Desforge, Y.Giomataris, T.Papaevangelou, A.Peyaud (CEA/DSM-IRFU)

Tuesday 13 June 2017,



Micromegas concept

Two-region gaseous detector separated by a Micromesh :

- Conversion region
 - Primary ionization
 - Charge drift towards A.R.
- Amplification region
 - Charge multiplication
 - Readout layout
 - Strips (1/2 D)
 - Pixels

Very strong and uniform electric field

- metallic micromesh (typical pitch 50μm)
- sustained by 50-100 μm pillars
- simplicity
- single stage of amplification
- fast and natural ion collection
- discharges non destructive



Mesh signal Pixels / strips signals

MICROMEGAS description + technologies (i)

Micro-mesh (cathode)

The metallic micro-mesh must be 5 to 30 μ m thick with needed equivalent wires densities ranging from 500 to 2000 Lines Per Inch (LPI). Stainless steel woven meshes, electroformed Nickel meshes, or chemically etched copper meshes are used. New products are needed for high LPI thin meshes.



Printed Circuit Board (anode PCB)

- $\checkmark\,$ It can be up to 1- 3 m² and down to 100 μm thin.
- ✓ Copper strips or pads can be ≈100 µm to few mm large and insulation between them as low as 50 µm.
- Copper is usually covered by a Ni/Au layer for a total thickness which must be kept as low as possible (down to 5 μm) with a « smooth » surface.



A Φ30 cm 12 layers PCB with 4000 x 4 mm² pads for the MINOS TPC (18000 blind vias)

Patented technology (CEA – EOS imaging) G. Charpak, Y. Giomataris, Ph. Rebourgeard, J-P Robert Y. Giomataris *et al.*, NIM A 376 (1996) 29



MICROMEGAS description + technologies (ii)

Patented technology (CEA - EOS imaging) Drift electrode + neutron converter G. Charpak, Y. Giomataris, Ph. Rebourgeard, J-P Robert Y. Giomataris et al., NIM A 376 (1996) 29 ✓ For thermal neutrons, it can be a thin aluminum foil or a metallic mesh covered by a **MICROMEGAS** is a parallel plate gaseous structure which uses An electroformed Ni 1-2 µm thick layer containing ¹⁰B (such mesh covered by a a thin metallic micromesh to define the high electric field region 2 µm thick B₄C layer as B₄C) or by a ≈100 µm thick ⁶Li layer. (Linköping Univ.) in which primary electrons are amplified by avalanche Low cost industriallized processes needed and collected on a micro-segmented Printed Circuit Board For high energy neutrons, a few mm \checkmark thick polyethylene (CH₂) sheet is used. neutrons Neutron to ionizing particles converter HV_{drift} ≈ -1000 V (10B, 6Li, Gd, CH₂) Micromegas technologies e- Drift region to realize the micro-mesh + anode PCB assembly up to 10 mm (E<1 kV/cm) **Bulk-micromegas** micro-bulk micromegas GAS e Technology transfer to be done On-going technology transfer e⁻ avalanche region Embedding of the mesh between Micromegas is built from a double 25-200 µm two layers of insulating pillars by sidded copper clad kapton foil by (E > 40 kV/cm) use of photolithography technics selective chemical etching of HV_{mesh} ≈ -500 V copper (mesh and anode strips) Copper segmented anode Base Material (gain tuning) and kapton (insulating pillars). FR4 Lamination of Vacrel Photo-imageable Mesh with voical Φ40 µm hole polyamide film with 100 um pitch Spacing pillars Positioning of Mesh To front-end Stainless steel Strip signal woven mesh pre-amplier (ground) Encapsulation Selective UV Kapton 50 µm exposure **Performances** Border frame Development Spacer Intrinsic low sensitivity to γ photons (gas) A 10x10 cm² micro-bulk (NEXT prototype) Contact to Mesh High spatial resolution (down to 100 µm) Fast signals (< 1 ns) Short recovery time (~150 ns) High rate capabilities (> MHz) A 34x36 cm² bulk-micromegas High gain (up to 10⁶) (T2K/TPC)

Service d'Electronique, Détecteurs, et Informatique (SEDI) - ESS industrial days, February 4-5th 2016, Paris, France (CSS) contact : Alain Delbart (alain.delbart@cea.fr

Micromegas applications



Micromegas R&D

Experiments @ CERNs: New detectors & Continuous improvement

- ≻ CAST []
 - d Microbulk development
- ➢ nTOF
 - I Microbulks for flux measurements
 - I Microbulks for fission measurements
 - XY-Microbulk

R&D for other projects

- > NMI3
- Schlumberger
- Picosecond

Detector technology R&D

- Piggyback
- Thin mesh
- Kapton mesh
- XY-Microbulk
- Small gap Microbulk
- Resistive Micromegas





Drift field	
typical 102-3 V/cn	n 🖌 🎽
Amplification field	
typical 10⁴⁻⁵ V/cm	
$\backslash A$	
Amplification	
gap: 50-100 μm	













Micromegas R&D

People involved at SEDI



eferrer



ioa



attie



Esther FERRER-RIBAS

DSM//IRFU/SEDI/DEPHYS Service d'Electronique, des

- Chef de laboratoire
- Chef de projet
- Membre du CSTS



delbart



tpapaeva



aunes

Stephan AUNE DSM//IRFU/SEDI/DIR Service d'Electronique,

Chef de projet

+ Fabian Jeanneau, Alan Peyaud, George Tsiledakis, Paul Serrano, Mariam Kebbiri...

Alain DELBART

DSM//IRFU/SEDI/DePhys Service d'Electronique, des

Thomas PAPAEVANGELOU

Service d'Electronique, des l

DSM//IRFU/SEDI/DEPHYS

- Chef de projet
- Membre du CSTS



Ioannis GIOMATARIS

DSM//IRFU/SEDI/DEPHYS Service d'Electronique, des

Chef de projet

David ATTIE

Chef de projet

Membre du CSTS

Responsable scientifique

DSM//IRFU/SEDI/DEPHYS

Service d'Electronique, des I

Membre du CU du service

Micromegas R&D

Main building - R1 Close collaboration with the detector Lab of De Oliveira, Rui PH-DT-DD 102/R-018 tel: 73745 163931 (Rui.de.Oliveira@cern.ch) CERN Geographic Information System > MAPCERN Other GIS Portal PH (1) (2) fficiel 200 (m) Bird's eye Street View Route Marie OURIE A new research has been set up. Please click here for more information



The bulk lab @ SEDI, CEA Saclay



Neutron detection with Micromegas

Neutron detection [] neutron to charge converter

- Solid converter: thin layers deposited on the drift or mesh electrode (¹⁰B, ¹⁰B₄C, ⁶Li, ⁶LiF, U, actinides...)
 - ✓ Sample availability & handling
 - ✓ Efficiency estimation
 - ★ Limitation on sample thickness from fragment range
 ⇒ limited efficiency
 - Not easy to record all fragments
- > Detector gas (³He, BF_3 ...)
 - ✓ Record all fragments
 - ✓ No energy loss for fragments \Rightarrow reaction kinematics
 - ✓ No limitation on the size \Rightarrow high efficiency
 - **×** Gas availability
 - Handling (highly toxic or radioactive gasses)
- Neutron elastic scattering
 - gas (H, He)
 - solid (paraffin etc.)
 - ✓ Availability
 - \checkmark High energies
 - ***** Efficiency estimation & reaction kinematics

Neutron detection with high efficiency (~50%):

- ³He crisis
- Increased demand for neutron detectors
 - →Science
 - →Homeland security
 - →Industry

Micromegas for neutrons

- Micro-Pattern Gaseous Detector (gain, fast timing, high rate, granularity, radiation hardness, simplicity...)
- Low mass budget
- Transparent to neutrons
- Large area detectors cheap & robust

Ingredients to build a simple counter

Gained lots of experience in Boron deposition

- Simple method with B powder @ SEDI (PatricK Magnier)
- Electrodeposition, Sputtering @ DRT (Ph. Bergonzo Lab)
- Collaboration with DRT & Linkoping University

Detector very interesting as a simple, portable, neutron counter for several facilities (i.e. LICORNE)





¹⁰B layer (thick!) deposited on the inner part of the chamber

The ¹⁰B layer is the less trivial part to build

- Material availability
- Deposition methode
 - ✓ Sputtering
 - ✓ Evaporation
 - Electrodeposition



Teflon / kapton joint

Gas tubes

The Schlumberger neutron counter







Performance



The multilayer concept (i)

- A boron layer thicker than 1-2 μm is not efficient due to the absorption of the reaction products
- Maximum efficiency that can be achieved in this case is of the order of 4-5 %
- One solution: a tower of detector-converter layers
 - ➔ Many detectors
 - Lots of material
- Alternative: a tower of converter layers for each detector: 10B deposited on thin metallic meshes
 - Less electronics
 - ➔ Less material

Difficulty: drift the produced charges to the detector through the mesh holes (proper configuration of the electric field)



The multilayer concept (ii)

- One module can be consisted of a double-face Micromegas facing 7+7 10B layers
- Such a module can be ~1 cm thick!
- > Material:
 - ✓ 0.2 0.3 µm PCB
 - ✓ 6 x 5 µm Ni
 - ✓ 2 x micromesh
 - ✓ 2 x 1 mm Aluminum case
- A stuck of such detectors can be used to increase efficiency
- Detector can be tilted by 45° in respect to the neutron direction.

Status:

- Monte-Carlo studies to optimize the electron transmission & sample thickness
- Prototype for performance studies



Concept

• Use developments of Micromegas technology in Saclay to demonstrate the feasibility of a large highefficiency neutron detector with several ${}^{10}B_{4}C$ thin layers

mounted inside the gas volume.

• Built a single detector unit prototype with overall dimension of ~ 15 x 15 cm² and a flexibility of modifying the number of layers of ${}^{10}B_4C$

neutron converters.

 Evaluate *bulk* (NMI3) / *microbulk* (SINE2020)

technologies for the construction of large sizes detectors made a mosaic of such detectors.



The NMI3 prototype

- Bulk Micromegas 5x5 cm²
- Ni frames 7x7 cm²
- Ni meshes 10% & 20% transparent
- Voltages applied with the help of kapton+Cu frames

Ni meshes double coated with 1.5 μm B₄C layers

- 10% 20% transparent
- 5, 20, 120 µm thick
- 50, 100, 500, 1000 LPI
- (Linköping University)











Detection efficiency – FLUKA MC (i)

Simplified geometry of a Micromegas prototype





Detection efficiency – FLUKA MC (ii)

A >50% thermal neutron efficiency is reached with a 2 cm stack of transfer meshes with B_4 C layers on both sides, and a proper electric field configuration



<image><figure><text>





5-layer prototype performance

Comparison with commercial ³He tube:

Count rate {³*He* / *MM*} = 5.5 Assuming ³He eff. ~ 95% → *MM eff* ~ 18%

Satisfactory result

but:

- Electron transmission too low when mesh thickness >> 5 μm
- Mesh deformed during B₄C deposition if thickness << 20 μm

Difficult to operate with more than 3 layers per unit with large area Ni meshes A single 2-mesh detector unit \rightarrow **F=7**, 5 **x B** C layers







Alternative 1: Kapton mesh (GEM-type)

12.5 µm Kapton mesh

- double-side coated with 3-4 μm Cu
- double-side coated with 1 μm Ni
- double-side coated with 1.5 μ m B₄C

 ΔV (10-50 V) applied between the two Cu layers \Box electric field strong enough for sufficient electron transmission

- Small voltage for top layer (< 500 V)</p>
- Small amplification possible to compensate electron losses (factor 2-3)
- Mesh is cheap and robust
 Big surfaces possible (1×0.5 m²)



Problem with ¹⁰B₄C deposition: thermal expansion. ➤ Use pure ¹⁰B

 Use a transparent mask (micromesh) during deposition of B₄C









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Alternative 2: Microbulk stack

- Microbulk is also a Kapton mesh, Cu-coated.
- Boron can be deposited on the Microbulk surface
 double efficiency
 - Ni or Au coating needed
 - × Same problem from thermal expansion coefficients
- Units can be stacked without limitation, using only 3 voltages (same cathode, mesh, anode voltages)
- ✓ Unit can be very thin (~1 mm)
- ✓ Low material budget
- Common / independent readout possible
- We have done some tests trying to deposit B₄C on Microbulk raw material.
- The deposition on the copper doesn't work, but on the Nickel coated copper it looks great, even after 2 months from the time the deposition was done.
- So, Nickel coated Microbulks seems it is the good way to proceed.
 International Papaevangelou



The <u>main advantage of the microbulk</u> detector is that there is no PCB and the readout pads are supported directly on 50 µm pillars which support the micromesh. Neutron scattering from such an arrangement should be very low and thus it should be possible to stack several layers one behind the other without adversely affecting the incoming neutrons.

SINE2020 Work Program

Original idea :

Move to microbulk to have thinner PCB layer and enable the stacking of detectors to improve the detection efficiency





- <u>Micro-bulk micromegas</u> \rightarrow Novel geometry of large scale neutron detector: a mosaic of micro-bulk micromegas coated with ${}^{10}B_{4}C$.
- <u>Simulations</u>: of first concept by placing 4 micro-bulk micromegas detector units, the neutron efficiency is 40%
- <u>A prototype</u> was designed and built: a modular 15x15x2 cm³ chamber in which up to 4 kapton micro-bulk micromegas can be stacked
- <u>Tests to deposit B</u> <u>C</u> on Micro-bulk raw material are on going
- <u>Simplified concept : Start testing</u> of a prototype where mesh is replaced by micro-bulk layer

Summary

We are examining possible ways to increase the detection efficiency for thermal neutrons, using solid neutron-to-charge convertors:

- A Micromegas equipped with several metallic (Ni) thin meshes coated with B₄C in both sides
 - Efficiency improvement as expected by the simulations
 - × Small electron transmission for thick (robust) meshes
 - × Deformation & fragility for thin meshes. Problem for large surface detectors
- A Micromegas equipped with GEM-type meshes coated with B₄C in both sides
 - Good electron transmission. Amplification during transmission easy
 - ✓ Small voltages
 - ✓ Robustness. Large surface detectors possible with low cost
 - \times Deposition of B₄C on the foil is difficult. Under study
- ➤ A stack of Microbulks coated with B₄C
 - Low material, thin detector
 - × Deposition of B_4C on the foil is difficult. Under study.



Micro Pattern Gaseous Detectors (MPGD)

Best technology for gaseous detector readout:

Micro Pattern Gaseous Detectors

- high granularity
- more robust than wires
- no E×B effect
- fast signal & high gain
- low ion feedback
- better ageing properties
- easier to manufacture
- lower cost
- big surfaces

Micromegas





GEMs





Bulk Micromegas technology



Bulk Micromegas technology

Bulk Micromegas: The pillars are attached to a woven mesh and to the readout plane

Typical mesh thickness 30 μm, gap 128 μm

- Uniformity, robustness, lower capacity, easy fabrication, no support frame, small surrounding dead region []
- Large area detectors feasible and robust!
- ✓ Curved surfaces
- ✓ Mass production!
- *Mesh thickness & bigger gap: some disadvantages in special applications*:
- Good but limited energy resolution (~18% @ 6keV)
- Restrictions on materials







Microbulk Micromegas technology



Microbulk Technology



By I. Giomataris and R. De Oliveira

Lower capacitance Under development

The pillars are constructed by **chemical processing** of a **kapton foil**, on which the mesh and the readout plane are attached. *Mesh is a mask for the pillars!*

Typical mesh thickness 5 μm, gap 50/25 μm

- Energy resolution (down to 10% FWHM @ 6 keV)
- Low intrinsic background & be recognition
- ✓ Low mass detector
- ✓ Very flexible structure
- Long termstability
- **×** Higher capacity
- ***** Fabrication process complicated
- Fragility / mesh can not be replaced





Energy and spatial resolution & stability

